

Notice of References Cited	Application/Control No. 09/988,685	Applicant(s)/Patent Under Reexamination SHIOYA ET AL.	
	Examiner David L. Hogans	Art Unit 2813	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-6,576,980	06-2003	Shao et al.	257/632
	B	US-			
	C	US-			
	D	US-			
	E	US-			
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Furusawa et al., Simple, reliable Cu/low-k interconnect integration using mechanically strong low-k dielectric material: silicon-oxycarbide (June 2000), IEEE, International technology conference, pages 222-224.
	V	
	W	
	X	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.